

UNION TECHNOLOGY CORP. 718 MONTEREY PASS RD MONTEREY PARK, CA 91754 TEL: 323-266-6603		DRAWN BY : MINH H.	DATE: 1/11/2012	PART NUMBER RG5550X7R226KB04AC	
		MFG. APPROVAL LAURIANO V.	ENGR. APPROVAL RAJ A.	Q.A. APPROVAL GARY K.	
		CUSTOMER REV. D		COMP. CODE N/A	CONFIG. CODE(S) RG5550X7R226KB04AC
CUSTOMER SPECIFICATION				FILE CODE Radial Lead	
ENCAP.	CHIP	X		SAME AS	
	CONF. COAT	N/A		A)	
LEADS	MAT'L	COPPER		B)	
	FINISH	SOLDER			
VOLTAGE CHAR.	X7R			STANDARD MANUF. SPEC.	
T.C.	± 15%			DIELECTRIC X7R	
TEMP. RANGE (DEG.C)	- 55C TO +125C			CHIP 429 x 3 (SPECIAL)	
WORKING VOLTAGE	50 VDC			LEAD P/N N/A	
CAP (pF) @ 1V	22,000,000 pF			TERMINATION SOLDERABLE TERM.	
TOL. @ 1K Hz	± 10%			FINISH N/A	
MAX. D.F.	2.50%				
IR @+ 25 DEG. C	30 M OHM				
IR @+125 DEG.C	3.0 M OHM		A = 0.291 INCH MAX (7.39 mm max)		
DWV @5 SEC	125 V DC		B = 0.600 ± 0.020 INCH (15.24 +/- 0.508 mm)		
			C = 0.535 INCH MAX (13.58 mm max)		
TEMP. CYCLE	X		D = 0.649 INCH MAX (16.48 mm max)		
BURN-IN 100 V 125 DEG. C	96 HOURS MIN		E = 0.150 - 0.170 INCH (3.81-4.32 mm)		
TESTING REQUIRED	X		F = 0.300 ± 0.020 INCH (7.62 +/- 0.508 mm)		
			1-2-3-4 Four Leads		
CAP/D.F	X		Lead Diameter = 0.035+/- 0.005 INCH		
DWV	X				
IR	X		Notes: 1. Solder dip leads in 10-88-2 solder before assembly		
DATA REQUIRED	X		2. Seal gaps between chips (blue paint)		
SPECIAL PACKAGING	PLASTIC TRAY		3. Black paint entire unit twice		
MARKING	X		4. Total 4 leads (2 on each side)		
M			5. Chips are horizontally mounted		
A	UTC				
R	RG5550X7R				
K	226KB04AC				
I	50V				
N	DATE CODE		Before Assembly, Attach Procedure MS-2090 to the traveler for assembly instructions.		
G					
DATE:	1/11/2012			D	
Notes: 1) No crack at meniscus					R
2) Packaging: use 0.187 thick HDPE sheet with holes(0.040) to protect lead from bending and label packaging trays "Fragile-Handle with Care".					E
3) Proper Pre-Heating of part is necessary before soldering part to P.C Board.					V
					I
					S
					I
					O
					N